

untested ICs to the holding and transfer mechanism; the supply unit having a plurality of supply trays storing a plurality of untested ICs; the supply mechanism comprising a supply suction mechanism for vacuum chucking an IC, a planar movement mechanism for moving the supply suction mechanism in a planar direction, and an elevator mechanism for moving the supply suction mechanism in a direction perpendicular to this plane, and removing untested ICs from the supply tray in the supply unit and supplying the untested ICs to the supply shuttle by moving the supply suction mechanism by means of the planar movement mechanism and elevator mechanism; the supply shuttle performing above the supply transfer unit an operation for receiving untested ICs removed from the supply tray by the supply suction mechanism of the supply mechanism at a first untested IC receiving position from the supply suction mechanism, then moving to a first untested IC transfer position for transferring the untested ICs to the supply transfer unit of the part transfer apparatus, and returning to the first untested IC receiving position when the transfer is completed; the transfer mechanism comprising a transfer suction mechanism able to move up and down, and configured to vacuum chuck an untested IC from the supply shuttle positioned at the first untested IC transfer position and rise, then descend, and transfer the untested IC to a tray of the supply transfer unit appearing directly thereunder by means of the supply shuttle moving to the first untested IC receiving position, by means of the transfer suction mechanism; the supply transfer unit being configured to sequentially cycle a plurality of trays by positioning the multiple trays one at a time to a second untested IC receiving position positioned directly below the first untested IC transfer position, and to a second untested IC transfer position for transferring untested ICs to the holding and transfer mechanism, moving an empty tray to the second untested IC receiving position after transferring untested ICs to the holding and transfer mechanism at the second untested IC transfer position, and moving a tray holding untested ICs to be tested next to the second untested IC transfer position; the ejection shuttle being configured to perform above the supply transfer unit an operation for receiving at a tested IC receiving position located directly above the second untested IC transfer position tested ICs processed by the process unit and removed from a tray of the supply transfer unit by the